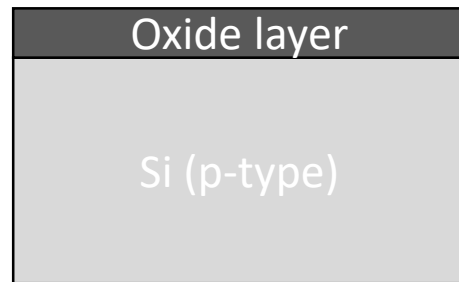
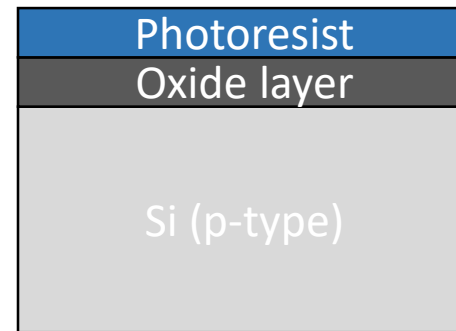


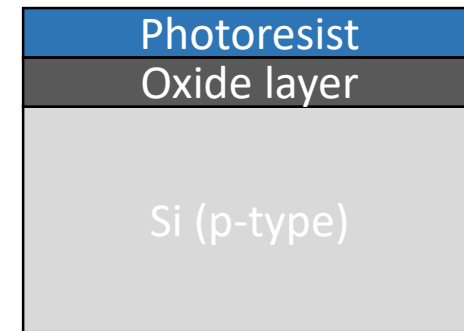
- 1) Base material
- Si wafer (p-type doped)



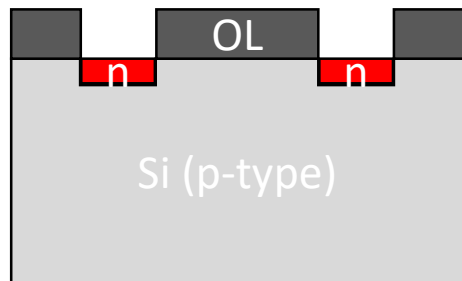
- 2) Growing of oxide layer
- Acts as insulation



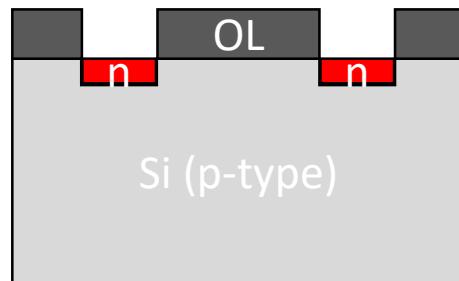
- 3) Applying photoresist



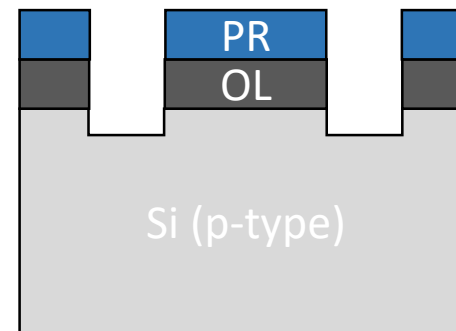
- 4) Photolithography



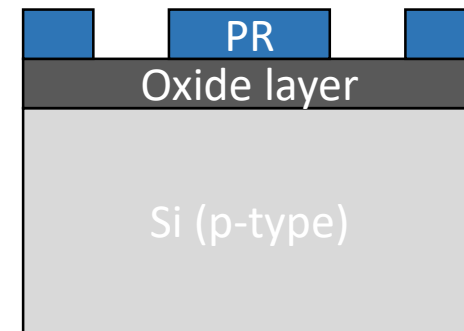
- 7) Doping



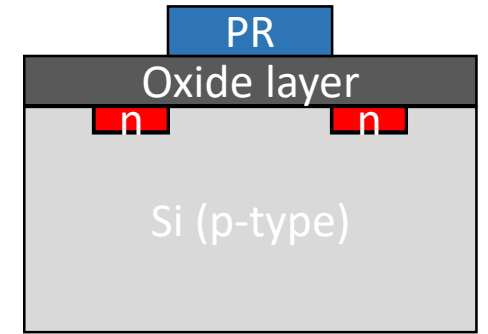
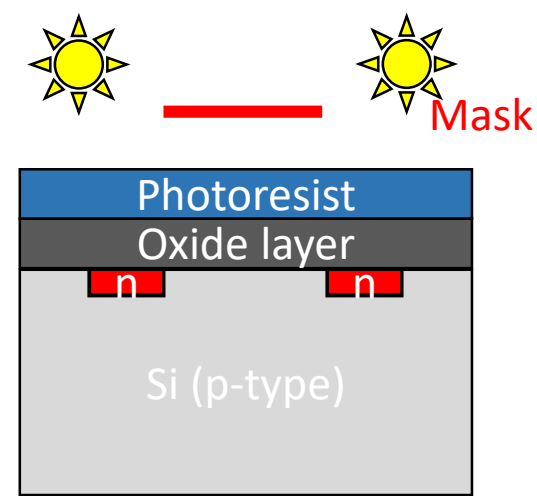
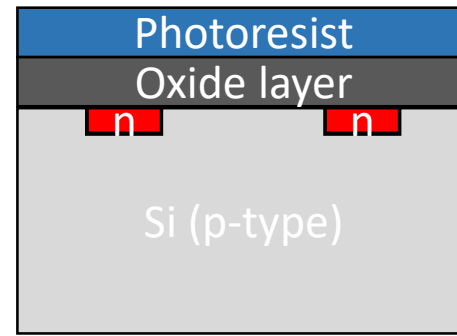
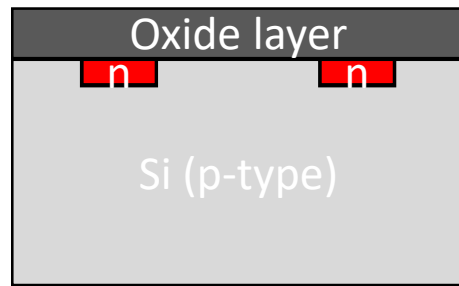
- 6) PR removing



- 6) Etching



- 5) Develop

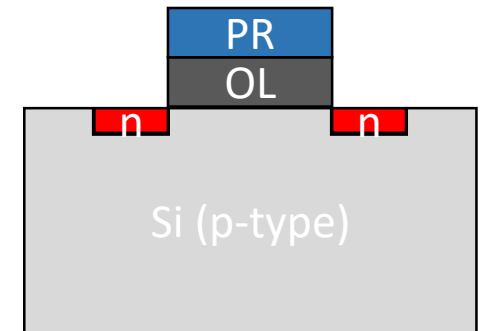
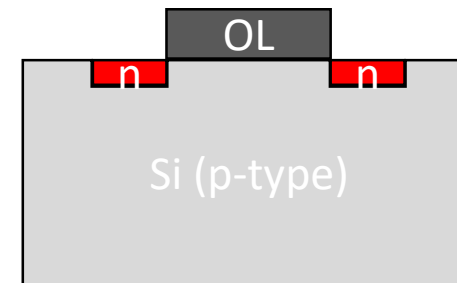
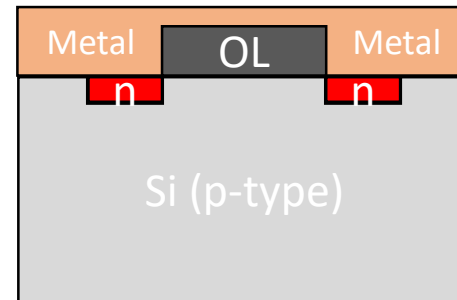
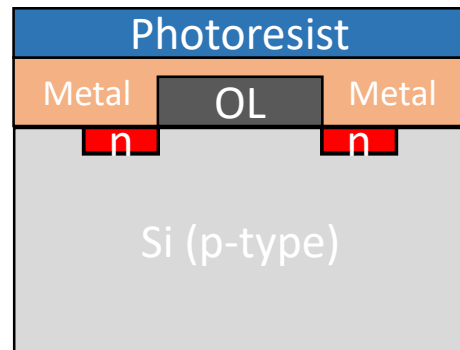


8) Oxide layer „fill up“
 • Is this called deposition?

9) Applying photoresist

10) Photolithography

11) Develop

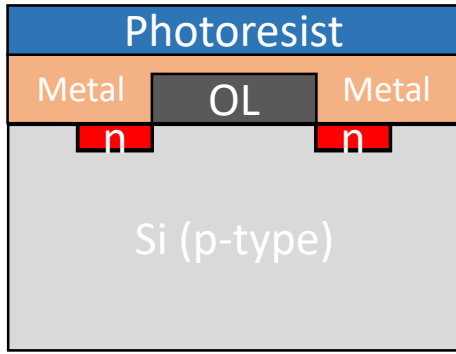
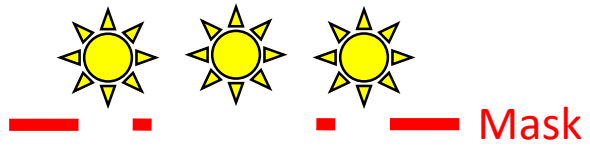


15) Applying photoresist

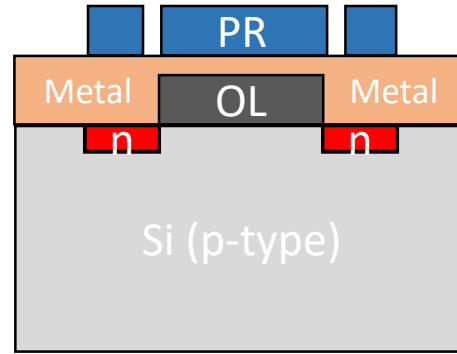
14) Metal deposition

13) PR removing

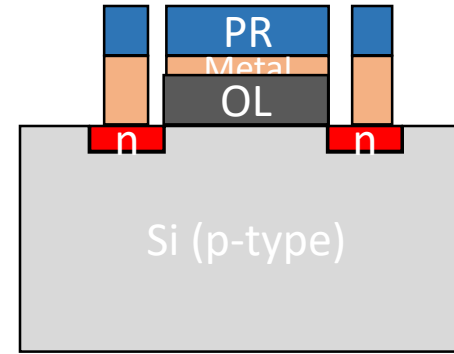
12) Etching



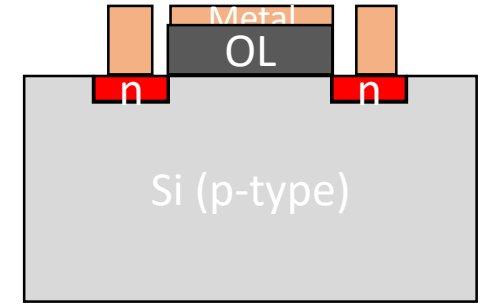
15) Photolithography



16) Develop



17) Etching



18) PR removing